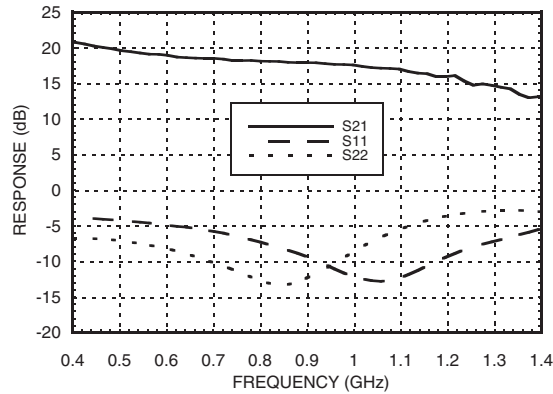




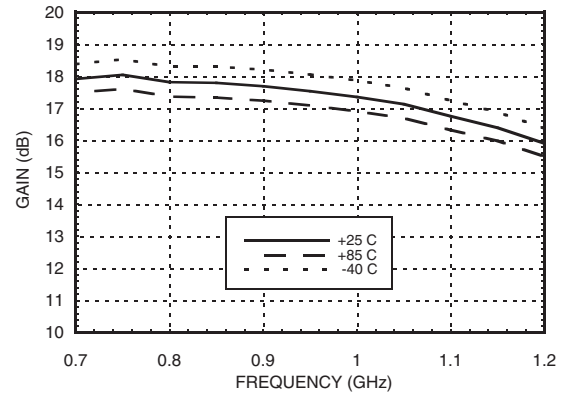
HMC454ST89 / 454ST89E

**InGaP HBT ½ WATT HIGH IP3
AMPLIFIER, 0.4 - 2.5 GHz**

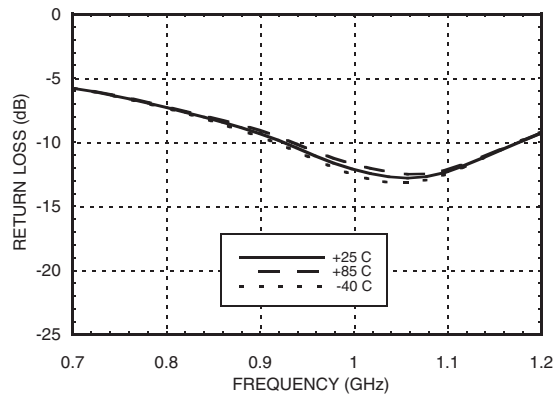
Broadband Gain & Return Loss @ 900 MHz



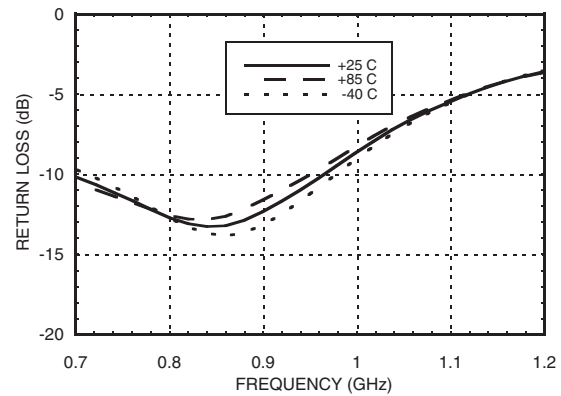
Gain vs. Temperature @ 900 MHz



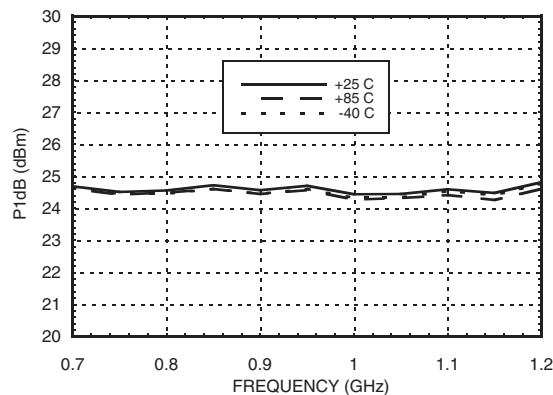
Input Return Loss vs. Temperature @ 900 MHz



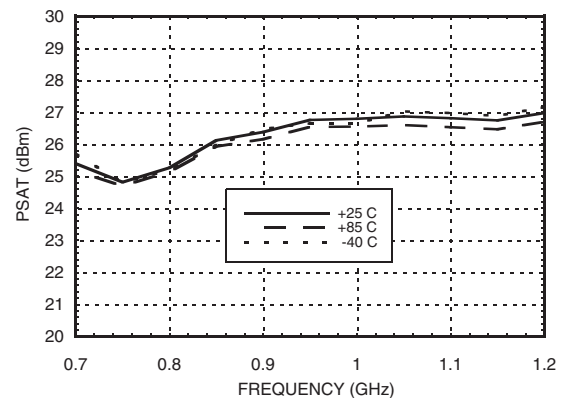
Output Return Loss vs. Temperature @ 900 MHz



P1dB vs. Temperature @ 900 MHz

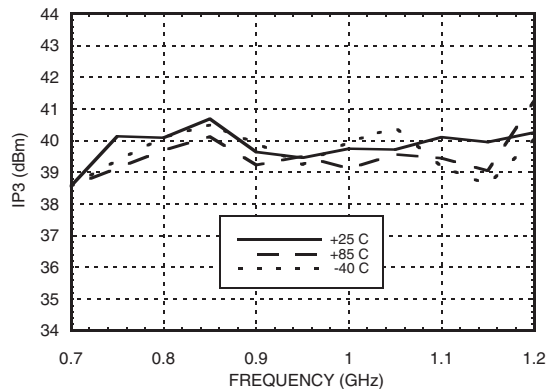


Psat vs. Temperature @ 900 MHz

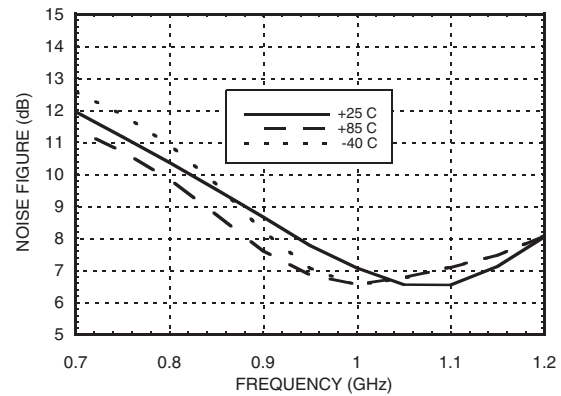




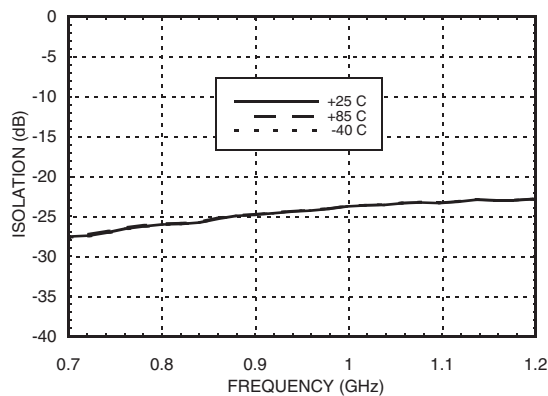
Output IP3 vs. Temperature @ 900 MHz



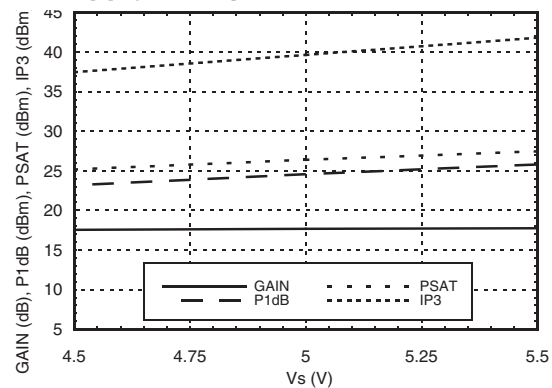
Noise Figure vs. Temperature @ 900 MHz



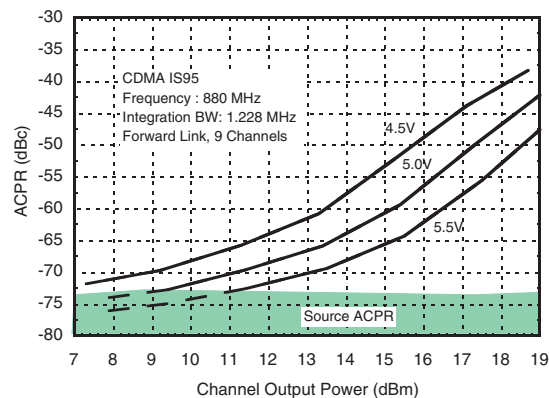
**Reverse Isolation
vs. Temperature @ 900 MHz**



**Gain, Power & Output IP3
vs. Supply Voltage @ 900 MHz**



**ACPR vs. Supply Voltage @ 880 MHz
CDMA IS95, 9 Channels Forward**

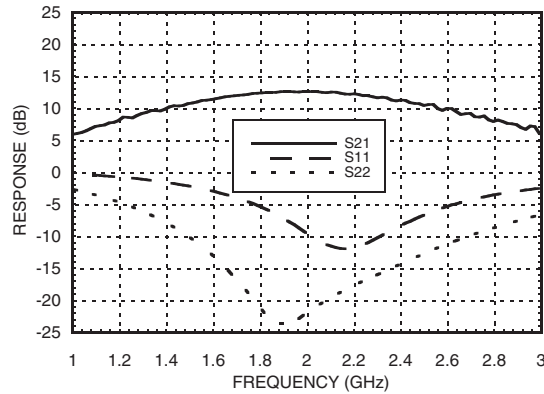




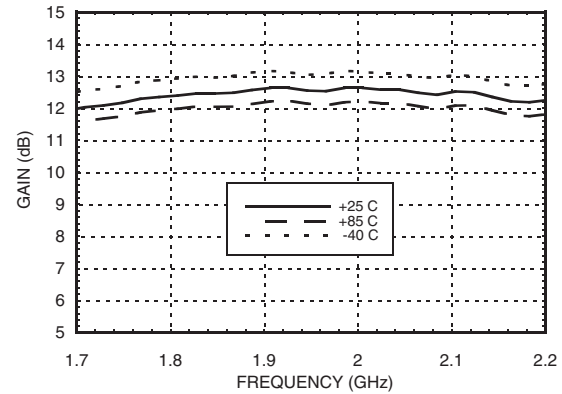
HMC454ST89 / 454ST89E

**InGaP HBT ½ WATT HIGH IP3
AMPLIFIER, 0.4 - 2.5 GHz**

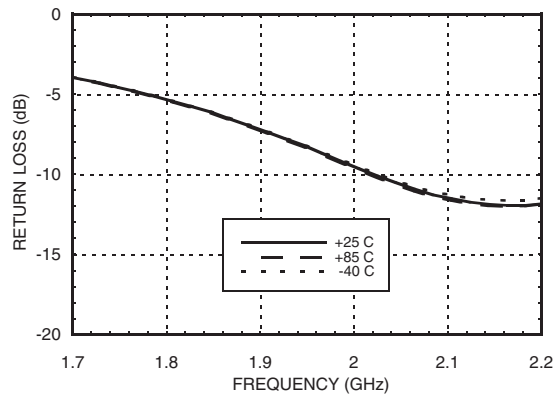
Broadband Gain & Return Loss @ 1960 MHz



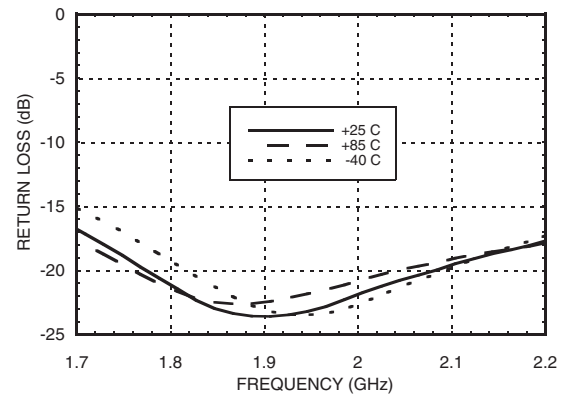
Gain vs. Temperature @ 1960 MHz



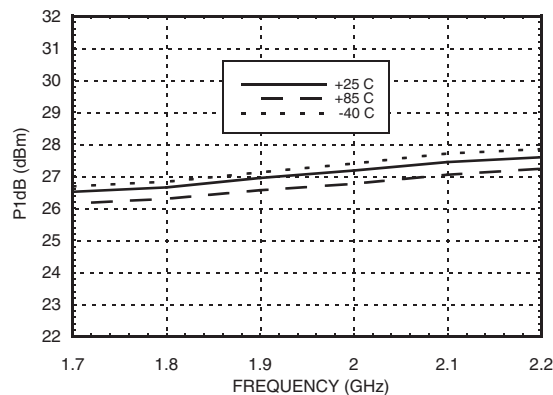
Input Return Loss vs. Temperature @ 1960 MHz



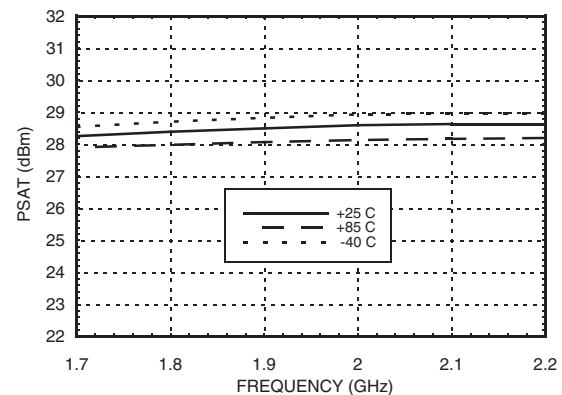
Output Return Loss vs. Temperature @ 1960 MHz



P1dB vs. Temperature @ 1960 MHz



Psat vs. Temperature @ 1960 MHz

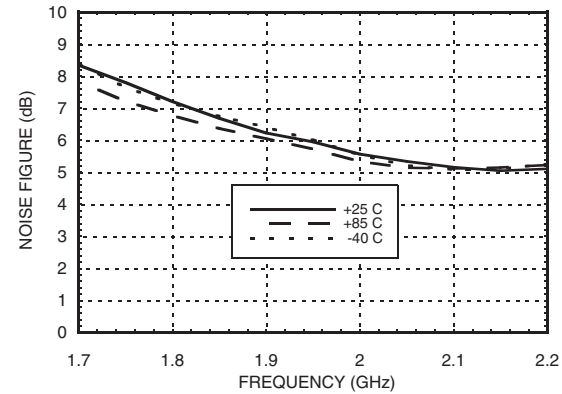




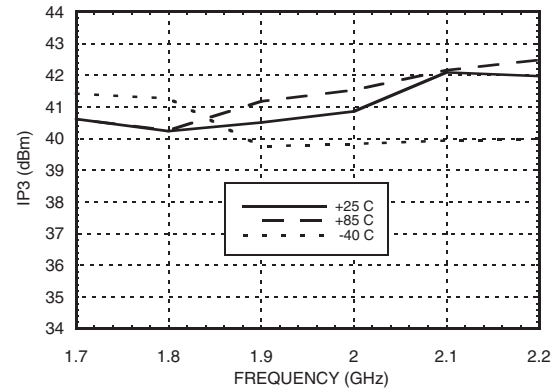
HMC454ST89 / 454ST89E

InGaP HBT ½ WATT HIGH IP3 AMPLIFIER, 0.4 - 2.5 GHz

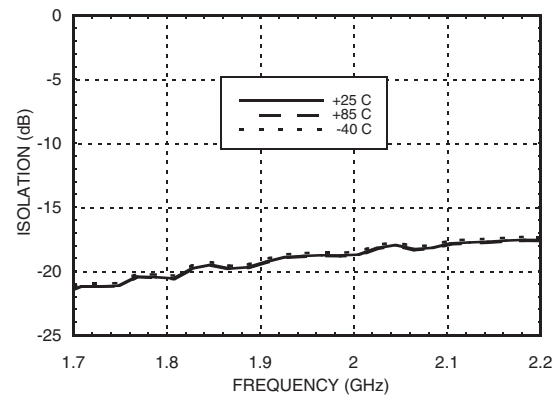
Noise Figure vs. Temperature @ 1960 MHz



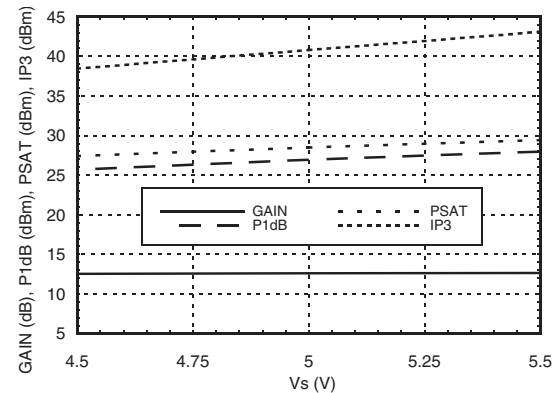
Output IP3 vs. Temperature @ 1960 MHz



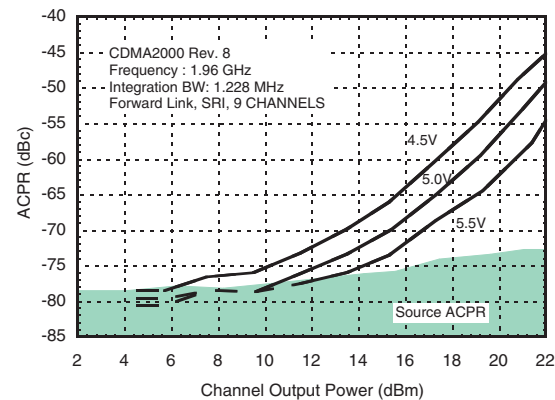
Reverse Isolation vs. Temperature @ 1960 MHz



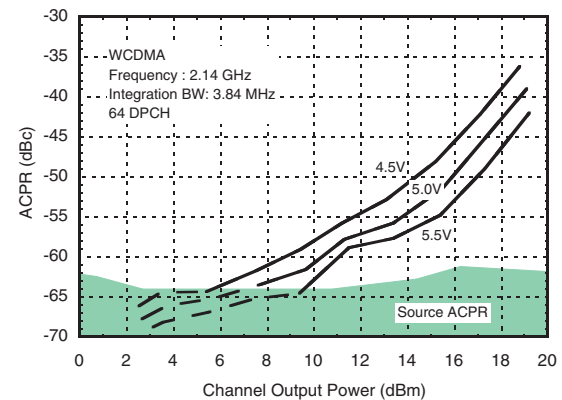
Gain, Power & Output IP3 vs. Supply Voltage @ 1960 MHz



ACPR vs. Supply Voltage @ 1.96 GHz CDMA 2000, 9 Channels Forward



ACPR vs. Supply Voltage @ 2.14 GHz W-CDMA, 64 DPCH



Absolute Maximum Ratings

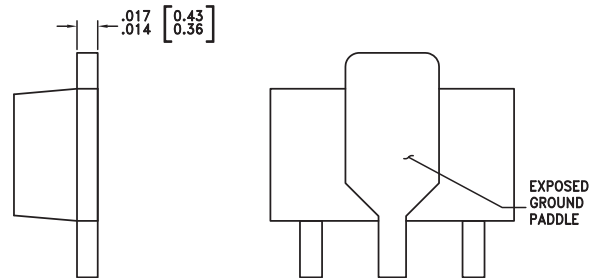
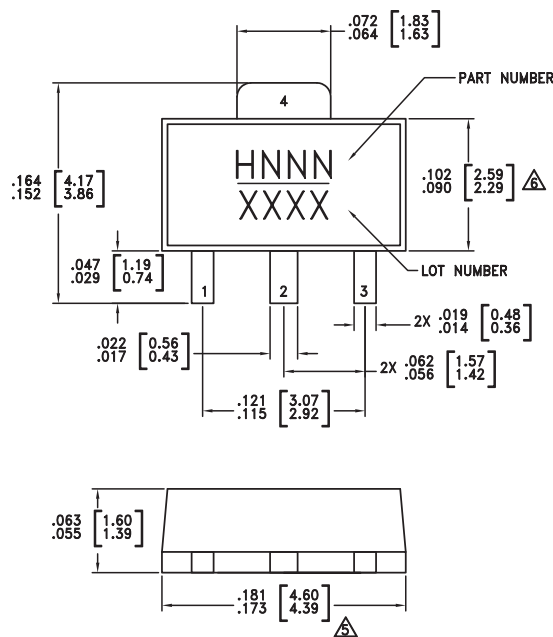
Collector Bias Voltage (Vcc)	+6.0 Vdc
RF Input Power (RFIN)(Vs = +5Vdc)	+25 dBm
Junction Temperature	150 °C
Continuous P _{diss} (T = 85 °C) (derate 13.6 mW/°C above 85 °C)	0.890 W
Thermal Resistance (junction to ground paddle)	73 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

9

Outline Drawing



NOTES:

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC454ST89	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	H454 XXXX
HMC454ST89E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	H454 XXXX

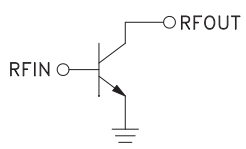
[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

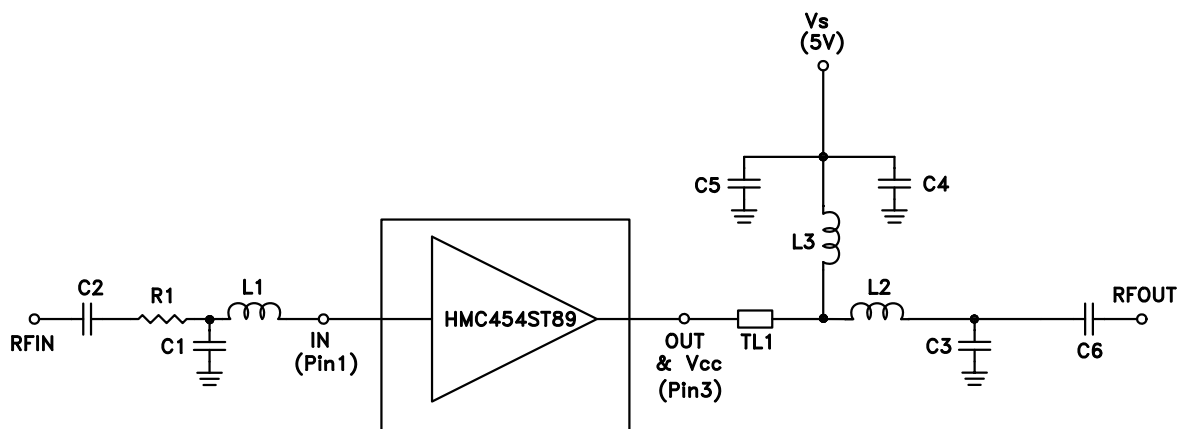


Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	RFIN	This pin is AC coupled. Off chip matching components are required. See Application Circuit herein.	
3	RFOUT	RF output and DC Bias input for the output amplifier stage. Off chip matching components are required. See Application Circuit herein.	
2,4	GND	These pins & package bottom must be connected to RF/DC ground.	

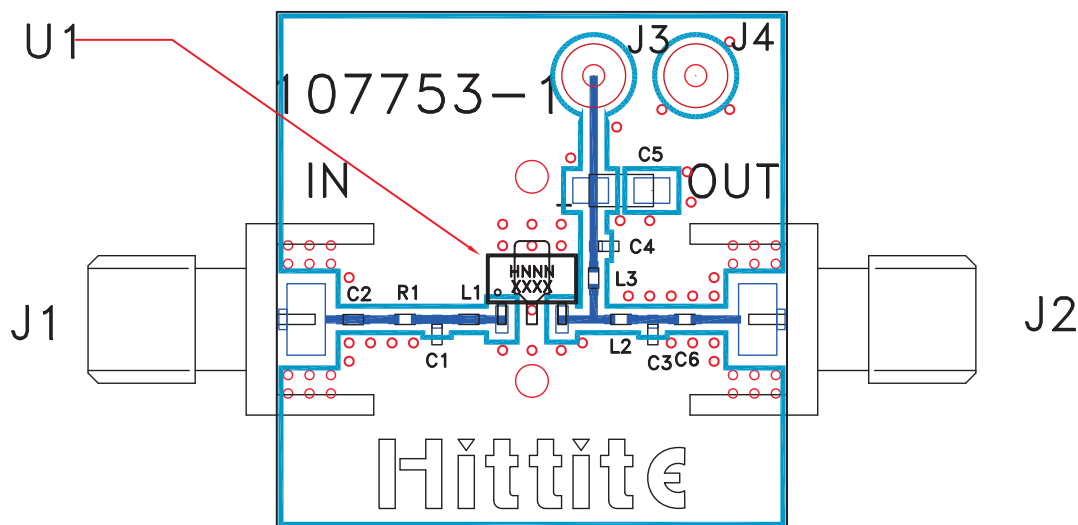
900 MHz Application Circuit, Compact Layout

This circuit was used to specify the performance for 894-960 MHz operation. This circuit will satisfy many applications from 700 to 1200 MHz. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1
Impedance	50 Ohm
Physical Length	0.050"
Electrical Length	2.5°
PCB Material: 10 mil Rogers 4350, Er = 3.48	

Recommended Component Values	
L1, L2	1 nH
L3	36 nH
R1	5.1 Ohms
C1	8 pF
C2	22 pF
C3	2.7 pF
C4, C6	100 pF
C5	2.2 μF

900 MHz Evaluation PCB

List of Materials for Evaluation PCB 107755 ^[1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3 -J4	DC Pins
C1	8 pF Capacitor, 0402 Pkg.
C2	22 pF Capacitor, 0402 Pkg.
C3	2.7 pF Capacitor, 0402 Pkg.
C4, C6	100 pF Capacitor, 0402 Pkg.
C5	2.2 µF Capacitor, Tantalum
L1, L2	1 nH Inductor, 0402 Pkg.
L3	36 nH Inductor, 0402 Pkg.
R1	5.1 Ohms
U1	HMC454ST89 / HMC454ST89E Linear Amp
PCB ^[2]	107753 Evaluation PCB, 10 mils

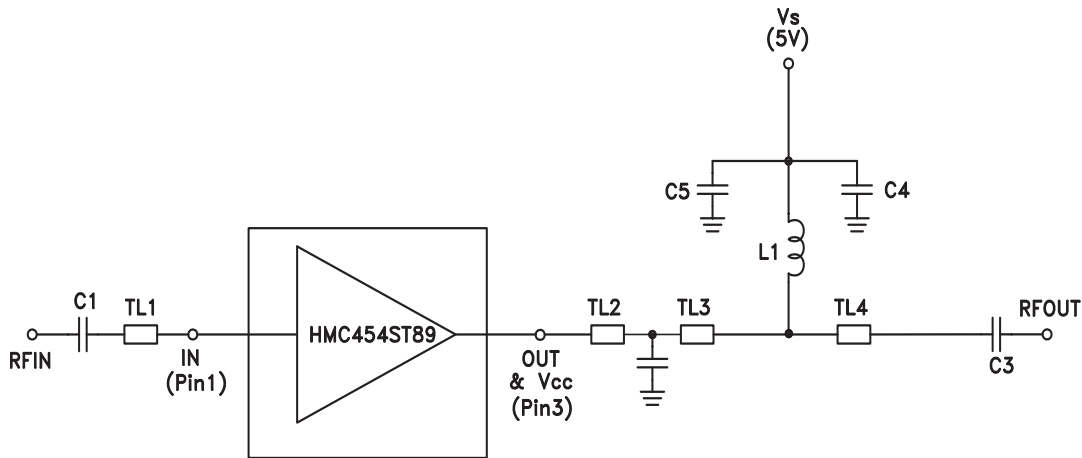
[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

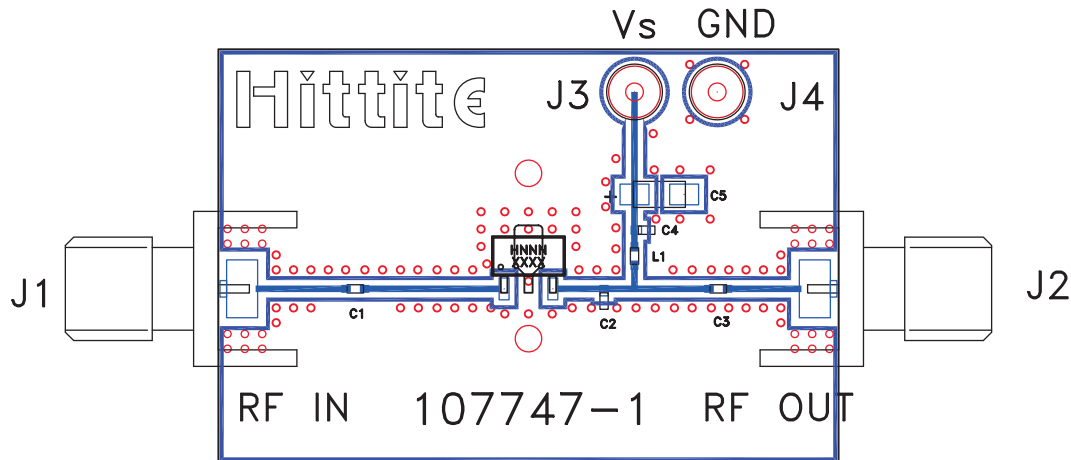
1960 & 2140 MHz Application Circuit

This circuit was used to specify the performance for 1800-2000 and 2000-2200 MHz operation. This circuit will satisfy many applications from 1700 to 2500 MHz. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1	TL2	T3	TL4
Impedance	50 Ohm	50 Ohm	50 Ohm	50 Ohm
Physical Length	0.32"	0.10"	0.07"	0.17"
Electrical Length	34°	11°	8°	18.5°
PCB Material: 10 mil Rogers 4350, Er = 3.48				

Recommended Component Values	
L1	8.2 nH
C1	1 pF
C2	1.2 pF
C3	3 pF
C4	100 pF
C5	2.2 μF

1960 & 2140 MHz Evaluation PCB

List of Materials for Evaluation PCB 107749 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3 - J4	DC Pins
C1	1.0 pF Capacitor, 0402 Pkg.
C2	1.2 pF Capacitor, 0402 Pkg.
C3	3.0 pF Capacitor, 0402 Pkg.
C4	100 pF Capacitor, 0402 Pkg.
C5	2.2 µF Capacitor, Tantalum
L1	8.2 nH Inductor, 0402 Pkg.
U1	HMC454ST89 / HMC454ST89E
PCB [2]	107747 Evaluation PCB, 10 mils

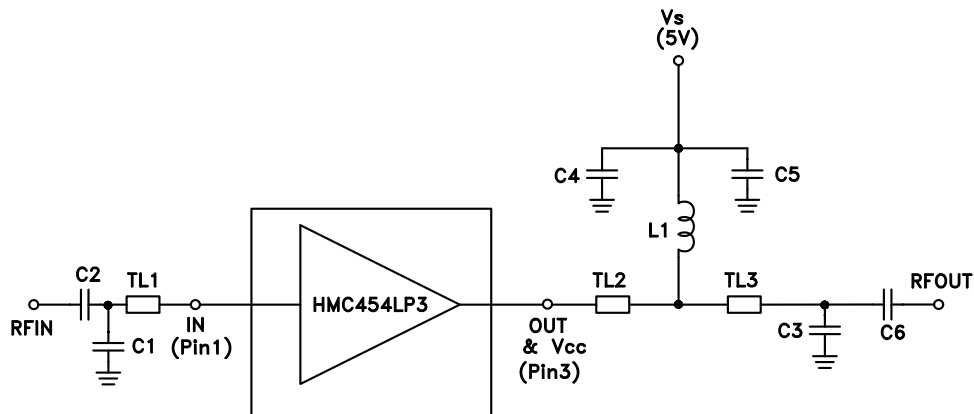
[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

Alternative 900 MHz Application Circuit, Optimal OIP3 Layout

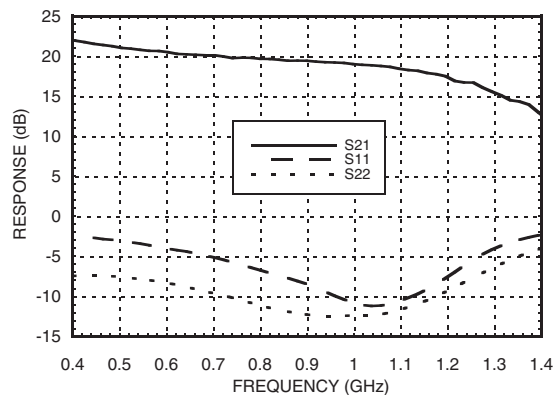
This alternate application circuit for 900 MHz applications features a resonating I/O structure on the PCB that, while using more PCB area, will improve output IP3 from +40 dBm to +42 dBm. This circuit will satisfy many applications from 700 to 1200 MHz as the typical performance below demonstrates. Contact the HMC Applications Group for assistance in optimizing performance for your application.



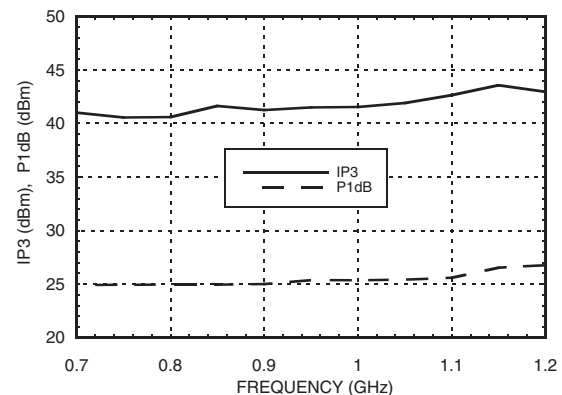
	TL1	TL2	TL3
Impedance	50 Ohm	50 Ohm	50 Ohm
Physical Length	0.35"	0.05"	0.53"
Electrical Length	18°	2.5°	27°
PCB Material: 10 mil Rogers 4350, Er = 3.48			

Recommended Component Values	
L1	18 nH
C1	4 pF
C2, C6	10 pF
C3	3 pF
C4	100 pF
C5	2.2 µF

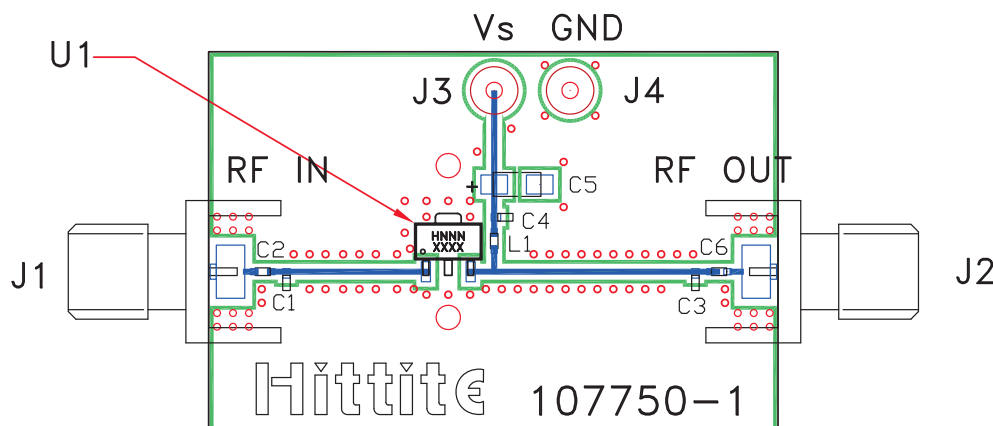
Broadband Gain & Return Loss



Output IP3 & P1dB



Alternate 900 MHz Evaluation PCB



List of Materials

Item	Description
J1 - J2	PCB Mount SMA Connector
J3 - J4	DC Pins
C1	4 pF Capacitor, 0402 Pkg.
C2, C6	10 pF Capacitor, 0402 Pkg.
C3	3.0 pF Capacitor, 0402 Pkg.
C4	100 pF Capacitor, 0402 Pkg.
L1	18 nH Inductor, 0402 Pkg.
U1	HMC454ST89 / HMC454ST89E
PCB*	107750 Evaluation PCB, 10 mils
* Circuit Board Material: Rogers 4350, Er = 3.48	

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.